



## Material Content Data Sheet



<b>Sales Product Name</b>		TLD5098EL		<b>Issued</b>		4. October 2018		
<b>MA#</b>		MA001927670						
<b>Package</b>		PG-SSOP-14-3		<b>Weight*</b>		83.09 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.131	2.57	2.57	25652	25652
leadframe	inorganic material	phosphorus	7723-14-0	0.009	0.01		104	
	non noble metal	zinc	7440-66-6	0.034	0.04		415	
	non noble metal	iron	7439-89-6	0.689	0.83		8293	
wire	non noble metal	copper	7440-50-8	27.978	33.67	34.55	336725	345537
	noble metal	gold	7440-57-5	0.207	0.25	0.25	2487	2487
	encapsulation	organic material	carbon black	1333-86-4	0.099	0.12		1193
encapsulation	plastics	epoxy resin	-	4.560	5.49		54884	
	inorganic material	silicondioxide	60676-86-0	44.908	54.05	59.66	540493	596570
leadfinish	non noble metal	tin	7440-31-5	0.976	1.17	1.17	11748	11748
plating	noble metal	silver	7440-22-4	0.768	0.92	0.92	9239	9239
glue	plastics	epoxy resin	-	0.182	0.22		2192	
	noble metal	silver	7440-22-4	0.546	0.66	0.88	6575	8767
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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